



GCSP-20LD SILICONE INTERFACE MATERIAL

GCSP-20LD is a low density conformable silicone based thermal interface pad.

Features

- 2.0 W/m K thermal conductivity
- Low density, ideal for weight critical applications
- Long term stability
- Good electrical insulation, >10kV

Configurations



PART NUMBER	TOTAL THICKNESS (MM)
GCSP-20LD-150x150-0.5	0.5
GCSP-20LD-150x150-3.0	3.0
GCSP-20LD-150x150-5.0	5.0

Properties

CHARACTERISTIC	TEST METHOD	VALUE
Colour	Visual	White/Pink
Reinforcement layer		Fibreglass
Thickness mm		0.5 to 5
Thermal conductivity W/m*K	ASTM D5470	2.0
Hardness (shore OO)	ASTM D2240	50
Specific gravity. g/cm ³	ASTM D792	1.9
Dielectric strength, kV/mm	ASTM D149	>10
Operation temperature (°C)	EN344	-50 to +150



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